

electrode of the circuit board.

11. An electronic component mounting apparatus comprising:

a device (7, 109, 200, 201) for sticking an
5 anisotropic conductive layer (10), in which an insulating resin mixed with an inorganic filler is mixed with a conductive particle (10a), to an electrode (5) of a circuit board (4) or an electronic component (1);

10 a device (93, 193) for forming a gold bump (3,
103), without leveling, by forming a ball (96, 96a) by an electric spark at a tip of a metal wire (95) on an electrode (2) of the electronic component (1) similarly to wire bonding and forming by thermocompression-bonding this to the electrode of the board with supersonic waves by
15 means of a capillary (93, 193);

a device (600) for mounting the electronic component on the electrode (5) of the circuit board (4) through positional alignment;

20 a device (620) for metallically bonding the gold bump to the electrode of the board with supersonic waves applied while shaping the tip so as to prevent collapse of a neck portion of the gold bump with a load applied from an upper surface of the electronic component by means of a tool (628); and

25 a device (8, 9) for bonding the electronic

component to the circuit board by hardening the insulating resin of the anisotropic conductive layer interposed between the electronic component and the circuit board while correcting warp of the board and crushing the bump
5 with a pressure force of not smaller than 20 gf per bump applied to the electronic component against the circuit board with heating by means of the tool (8), so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

10 12. An electronic component mounting method as claimed in any one of claims 10 through 11, wherein
the device (93, 193) for forming the gold ball (96a) has the capillary, which has a tip shape provided with no flat portion to be brought in contact with the gold
15 ball and of which a chamfer angle (θ_c) is not greater than 100°, and the gold bump that has an approximately conically shaped tip is formed on the electrode of the electronic component by the capillary.

13. An electronic component mounting apparatus
20 comprising:

a device (7, 109, 200, 201) for sticking an anisotropic conductive layer (10), in which an insulating resin mixed with an inorganic filler is mixed with a conductive particle (10a), to a circuit board (4) or an
25 electronic component (1);

a device (93, 193) for forming a bump (3, 103), without leveling, by forming a ball (96, 96a) by an electric spark at a tip of a metal wire (95) on an electrode (2) of the electronic component (1) similarly to
5 wire bonding and forming this on the electrode of the board by means of a capillary (93, 193);

a device (600) for mounting the electronic component on the electrode (5) of the circuit board (4) through positional alignment; and

10 a device (8, 9) for hardening the insulating resin interposed between the electronic component and the circuit board while correcting warp of the board with a pressure P1 applied as a pressure force to the electronic component against the circuit board and heat applied from
15 an upper surface of the electronic component by means of a tool (8) heated to a specified temperature and subsequently bonding the electronic component to the circuit board while alleviating a stress caused when hardening the insulating resin of the anisotropic conductive layer by reducing the
20 pressure force to a pressure P2 lower than the pressure P1 after a lapse of a specified time, so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

14. An electronic component mounting method as
25 claimed in any one of claims 1 through 3, wherein a mean